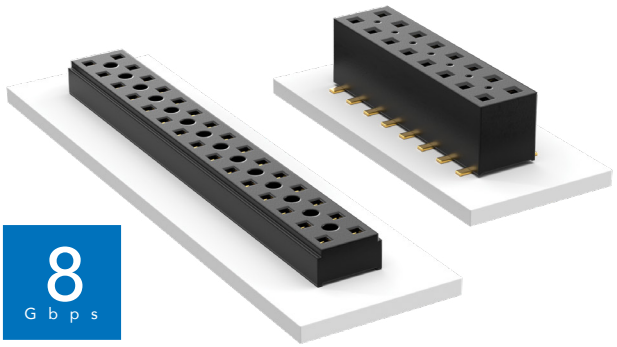
COST-EFFECTIVE & DUAL WIPE SOCKETS

8 Gbps

(2.00 mm) .0787" PITCH • TLE/CLT SERIES



TLE
Mates:
TMMH, TMM, MTMM, MMT, TW, LTMM, ZLTMM, TCMD, TSH

CLT
Mates:
TMM, TMMH, MTMM, MMT, TW, TSH

SPECIFICATIONS

TLE
Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating (TLE/TMMH):
3.2 A per pin (2 pins powered)
Voltage Rating:
406 VAC/574 VDC
Insertion Depth:
(2.08 mm) .082" to
(4.37 mm) .172" with
(0.38 mm) .015" wipe,
pass-through, or
(3.35 mm) .132" min
for bottom entry

CLT
Same as TLE except:
Plating:
Sn or Au over 50 µ" (1.27 µm) Ni
Current Rating (CLT/TMMH):
4.2 A per pin (2 pins powered)
Voltage Rating:
405 VAC/573 VDC
Insertion Depth:
Top Entry=
(1.40 mm) .055" minimum
Bottom Entry=
(2.57 mm) .101" minimum
(add board thickness for
correct post OAL)
Max Cycles:
100 with 10 µ" (0.25 µm) Au

PROCESSING

TLE
Lead–Free Solderable: Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-26)
(0.15 mm) .006" max (27-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

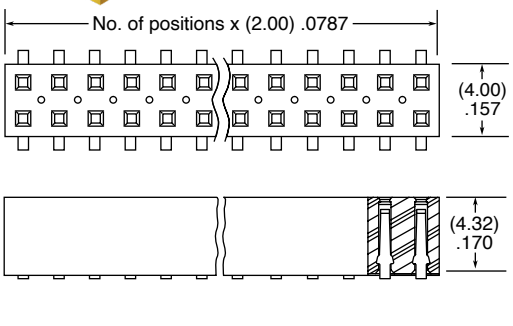
CLT
Same as TLE except:
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-25)
(0.15 mm) .006" max (26-34)*
(0.20 mm) .008" max (35-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

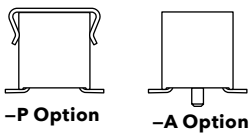
Note:
Some lengths, styles and options are non-standard, non-returnable.

TLE – 1 – NO. PINS PER ROW – 01 – PLATING OPTION – DV – OPTIONS

TIGER™ BEAM CONTACT

NO. PINS PER ROW: 02 thru 50





PLATING OPTION

–G
= 10 µ" (0.25 µm) Gold

OPTIONS

–A
= Alignment Pin (3 positions minimum)

–K
= (5.00 mm) .197" DIA Polyimide Film Pick & Place Pad (3 positions minimum)

–P
= Metal Pick & Place Pad (4 positions minimum)

–TR
= Tape & Reel Packaging (2-37 positions only)

-FR
= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (2-37 positions only)

CLT – 1 – NO. PINS PER ROW – LEAD STYLE – PLATING OPTION – D – OTHER OPTIONS

TIGER™ CLAW CONTACT

NO. PINS PER ROW: 02 thru 50

LEAD STYLE

–01
= Through-hole

–02
= Surface Mount

–03
= Through-hole

ALSO AVAILABLE
Contact Samtec
Other Platings

PLATING OPTION

–F
= Gold flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–G
= 10 µ" (0.25 µm) Gold on contact, Gold flash on tail

OTHER OPTIONS

All options require Style –02

–BE
= Bottom Entry (Required for bottom entry applications)

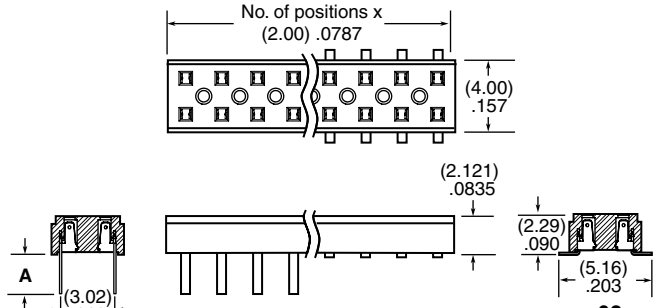
–A
= Alignment Pin (3 positions minimum) Metal or plastic at Samtec's discretion

–K
= (5.00 mm) .197" DIA Polyimide Film Pick & Place Pad (04 thru 50 only)

–P
= Pick & Place Pad (4 positions minimum) (Not always necessary for auto placement.)

–TR
= Tape & Reel (36 positions max)

–FR
= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (36 positions max)



LEAD STYLE	A
–01	(2.16) .085
–03	(2.95) .116

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.